

## 80V N-Channel MOSFETs

### General Description

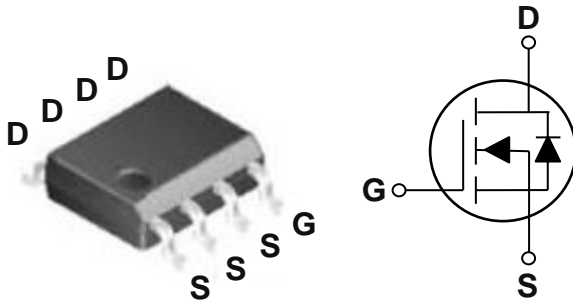
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	R <sub>DS(ON)</sub>	I <sub>D</sub>
80V	8mΩ	12A

### Features

- 80V, 12A, R<sub>DS(ON)</sub> = 8mΩ @V<sub>GS</sub> = 10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### SOP8 Pin Configuration



### Applications

- Networking
- Load Switch
- LED applications

### Absolute Maximum Ratings

T<sub>c</sub>=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	80	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub>	Drain Current – Continuous (T <sub>A</sub> =25°C)	12	A
	Drain Current – Continuous (T <sub>A</sub> =70°C)	9.6	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	48	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	125	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	50	A
P <sub>D</sub>	Power Dissipation (T <sub>A</sub> =25°C)	2	W
	Power Dissipation – Derate above 25°C	0.016	W/°C
T <sub>STG</sub>	Storage Temperature Range	-50 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-50 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	62.5	°C/W



# FTK8982B

## 80V N-Channel MOSFETs

### Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

#### Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	80	---	---	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V, T <sub>J</sub> =25 °C	---	---	1	uA
		V <sub>DS</sub> =48V, V <sub>GS</sub> =0V, T <sub>J</sub> =85 °C	---	---	10	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA

#### On Characteristics

R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =6A	---	6.7	8	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =5A	---	9.4	12.2	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.2	1.6	2.5	V
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =10V, I <sub>D</sub> =3A	---	10	---	S

#### Dynamic and switching Characteristics

Q <sub>g</sub>	Total Gate Charge <sup>3, 4</sup>	V <sub>DS</sub> =40V, V <sub>GS</sub> =10V, I <sub>D</sub> =10A	---	31.3	47	nC
Q <sub>gs</sub>	Gate-Source Charge <sup>3, 4</sup>		---	3.9	5.9	
Q <sub>gd</sub>	Gate-Drain Charge <sup>3, 4</sup>		---	9.5	14	
T <sub>d(on)</sub>	Turn-On Delay Time <sup>3, 4</sup>	V <sub>DD</sub> =40V, V <sub>GS</sub> =10V, R <sub>G</sub> =6Ω I <sub>D</sub> =8A	---	22	33	ns
T <sub>r</sub>	Rise Time <sup>3, 4</sup>		---	16	24	
T <sub>d(off)</sub>	Turn-Off Delay Time <sup>3, 4</sup>		---	40	60	
T <sub>f</sub>	Fall Time <sup>3, 4</sup>		---	31	47	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =40V, V <sub>GS</sub> =0V, F=1MHz	---	1720	2580	pF
C <sub>oss</sub>	Output Capacitance		---	350	525	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	10.5	16	
R <sub>g</sub>	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, F=1MHz	---	1.1	---	Ω

#### Drain - Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	12	A
I <sub>SM</sub>	Pulsed Source Current		---	---	24	A
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =1A, T <sub>J</sub> =25 °C	---	---	1	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>R</sub> =30V, I <sub>S</sub> =10A	---	35	---	ns
Q <sub>rr</sub>	Reverse Recovery Charge	di/dt=100A/μs, T <sub>J</sub> =25 °C	---	35	---	nC

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. V<sub>DD</sub>=25V, V<sub>GS</sub>=10V, L=0.1mH, I<sub>AS</sub>=50A., R<sub>G</sub>=25Ω, Starting T<sub>J</sub>=25 °C.
3. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
4. Essentially independent of operating temperature.

## 80V N-Channel MOSFETs

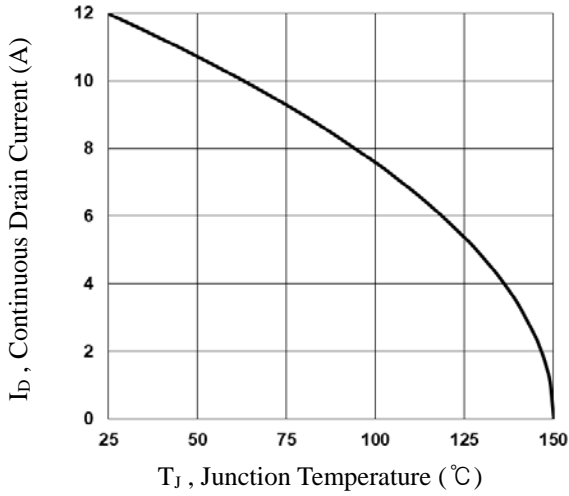


Fig. 1 Continuous Drain Current vs. T<sub>J</sub>

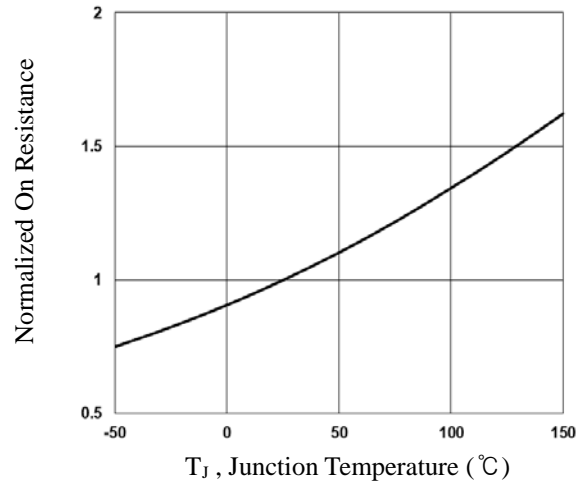


Fig. 2 Normalized R<sub>DS(on)</sub> vs. T<sub>J</sub>

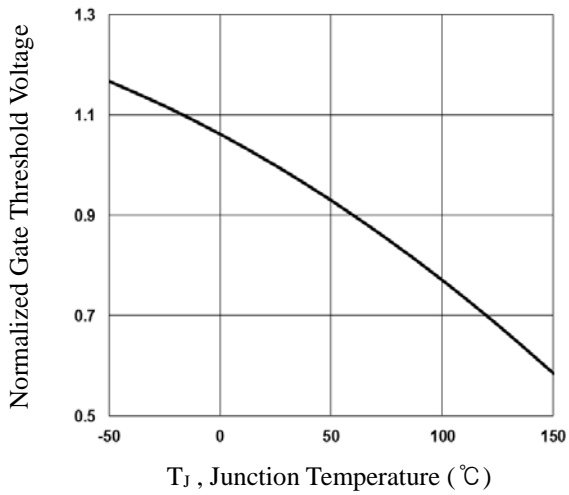


Fig. 3 Normalized V<sub>th</sub> vs. T<sub>J</sub>

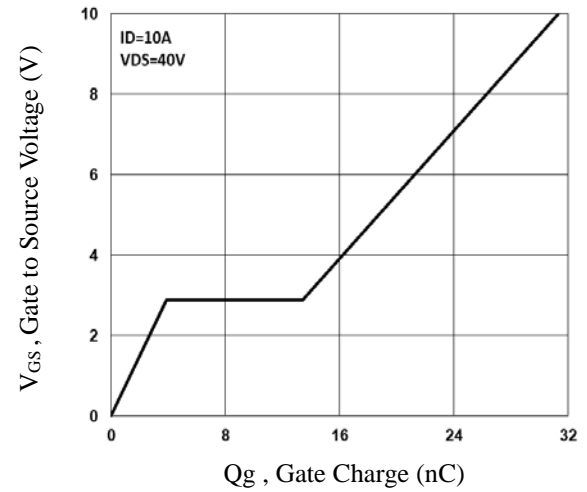


Fig. 4 Gate Charge Characteristics

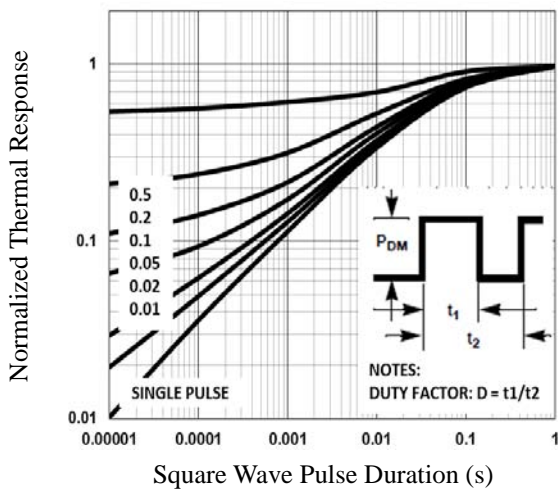


Fig. 5 Normalized Transient Impedance

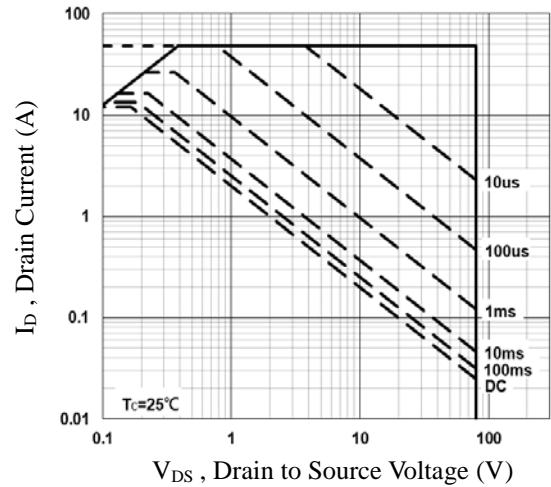


Fig. 6 Maximum Safe Operation Area



# FTK8982B

## 80V N-Channel MOSFETs

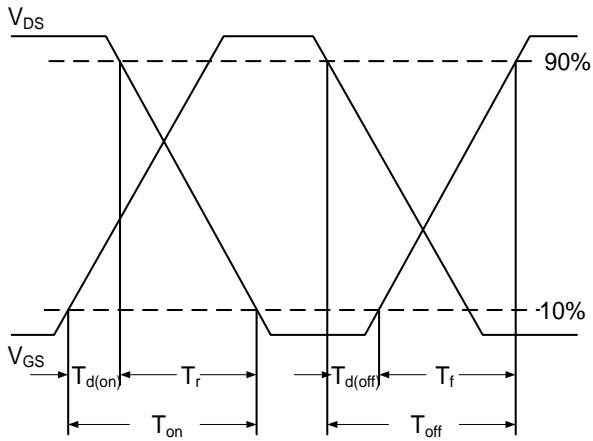


Fig. 7 Switching Time Waveform

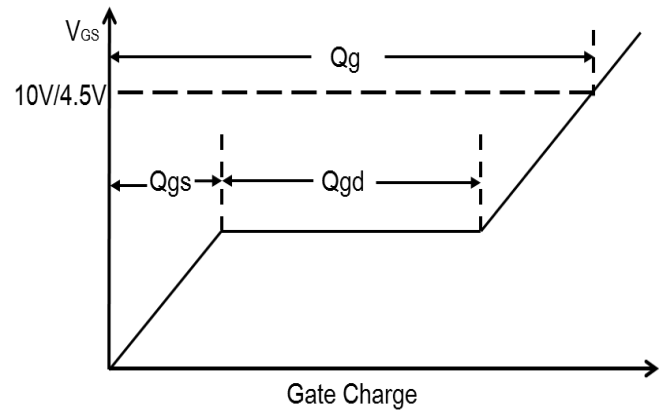


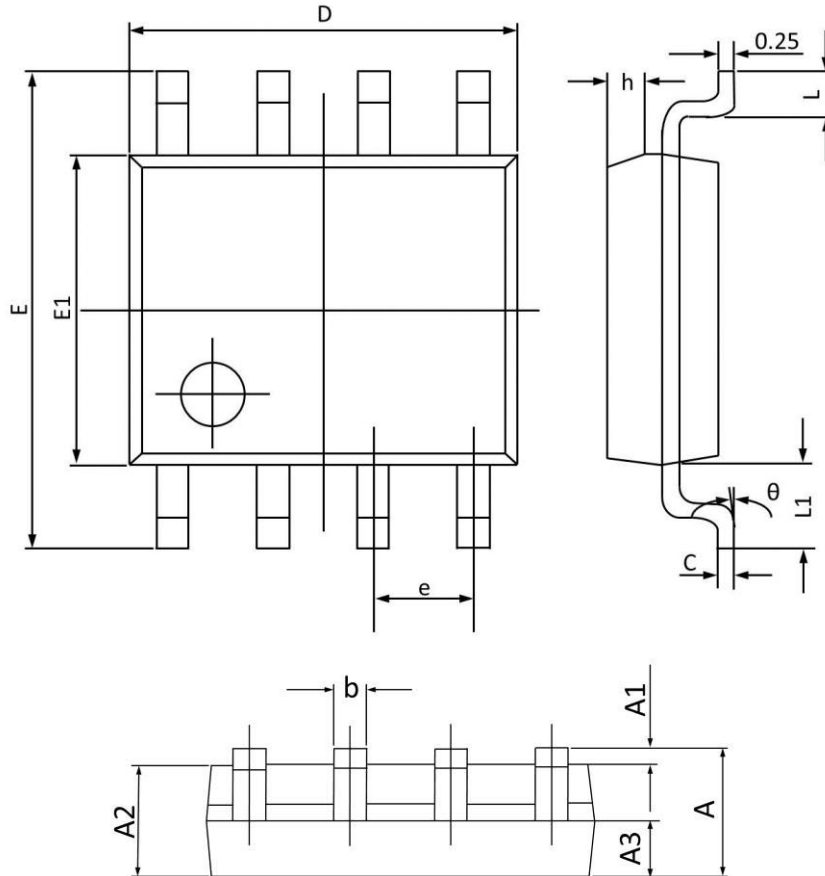
Fig. 8 Gate Charge Waveform



# FTK8982B

## 80V N-Channel MOSFETs

### SOP8 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.068
A1	0.100	0.250	0.004	0.009
A2	1.300	1.500	0.052	0.059
A3	0.600	0.700	0.024	0.027
b	0.390	0.480	0.016	0.018
c	0.210	0.260	0.009	0.010
D	4.700	5.100	0.186	0.200
E	5.800	6.200	0.229	0.244
E1	3.700	4.100	0.146	0.161
e	1.270(BSC)		0.050(BSC)	
h	0.250	0.500	0.010	0.019
L	0.500	0.800	0.019	0.031
L1	1.050(BSC)		0.041(BSC)	
θ	0°	8°	0°	8°